505109006 09/24/2018

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5155766

SUBMISSION TYPE:	NEW ASSIGNMENT
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NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KI JUN SUNG	09/14/2018

RECEIVING PARTY DATA

Name:	SK HYNIX INC.	
Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB	
City:	ICHEON-SI GYEONGGI-DO	
State/Country:	KOREA, REPUBLIC OF	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16140229

CORRESPONDENCE DATA

Fax Number: (630)323-0335

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: uspto.actions@wpapat.com

Correspondent Name: WILLIAM PARK & ASSOCIATES LTD. **Address Line 1:** 930 N. YORK ROAD, SUITE 201

Address Line 4: HINSDALE, ILLINOIS 60521

ATTORNEY DOCKET NUMBER:	PA3475-0	
NAME OF SUBMITTER:	W. WILLIAM PARK	
SIGNATURE:	/W. William Park/	
DATE SIGNED: 09/24/2018		
	This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 1

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PATENT 505109006 REEL: 046954 FRAME: 0828

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention	SEMICONDUCTOR PACKAGES INCLUDING A MULTI-CHIP STACK AND METHODS OF FABRICATING THE SAME		
Declaration	PCT/KR####################################	or or PCT international application number	
Assignment	NOW, THEREFORE, in consideration of the sum of one dollar (\$1), the receipt whereof is acknowledge, and other good and valuable consideration, I, by these presents do sell, assign and transfer unto said assignee(s) SK hynix Inc. 2091, Gyeongchung-daero, Bubal-eub, Icheon-si, Gyeonggi-do, Republic of Korea and the heirs, successors, assigns and legal representatives of the assignee(s) the full and exclusive right to the said invention in the United States and in its territorial possessions and in any and all foreign gountries any and all improvements thereof, the entire rights, title and interest in angolo any and all Patents which may be granted therefore in the United States. I hereby authorize and request the Director of the U.S. Patent and Trademark Office to issue said United States Patent to said assignee(s), of the entire right, title, and interest in angolo at the same, for his sole use and for the use of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made. I agree promptly upon request of the assignee(s), its heirs, successors, assigns and legal representatives of the assignee(s) to communicate any facts known to it respecting the patent and the invention set forth therein, and to execute and deliver without further compensation any power of attorney, Assignment, application, whether original, continuation, divisional or reissue, or other papers that may be necessary. I hereby covenant that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale. I further covenant that assignee(s) will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to me and will testify as to the same in any litigation related thereto and will promptly execute and deliver to		
Legal Name Of Inventor	Inventor Name (First Middle LAST):	Ki Jun SUNG	
	Inventor Signature: Date:	KT Ju Sung.	
	na(e:	09 114 12018	

A total of ____ supplemental sheet(s) are attached hereto for additional inventors, if any.

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SK hynix

PATENT REEL: 046954 FRAME: 0829